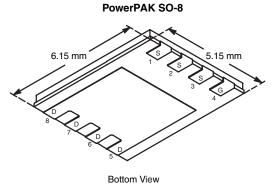


RoHS COMPLIANT

Vishay Siliconix

N-Channel Reduced Q_g, Fast Switching MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)		
30	0.008 at V _{GS} = 10 V	18		
	0.011 at V _{GS} = 4.5 V	15		



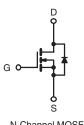
Ordering Information: Si7860DP-T1 Si7860DP-T1-E3 (Lead (Pb)-free)

FEATURES

- TrenchFET[®] Power MOSFET
- PWM Optimized for High Efficiency
- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07 mm Profile
- 100 % Rg Tested

APPLICATIONS

- Buck Converter
 High Side or Low Side
 - Synchronous Rectifier
 - Secondary Rectifier



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ess otherwise	noted		
Parameter		Symbol	10 secs	Steady State	Unit
Drain-Source Voltage		V _{DS}	30		v
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current (T 150 °C) ⁸	T _A = 25 °C	I _D	18	11	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		15	8	
Pulsed Drain Current		I _{DM}	± 50		А
Continuous Source Current (Diode Continuous) ^a		۱ _S	4.1	1.5	
Avalanche Current	L 0.1 mH	I _{AS}	30		
Single Pulse Avalanche Energy		E _{AS}	45		mJ
Mariana Damar Diasia atian ⁸	T _A = 25 °C		5	1.8	W
Maximum Power Dissipation ^a	T _A = 70 °C		3.2	1.1	vv
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150 260		°C
Soldering Recommendations (Peak Temperature) ^{b,c}					ĴĊ

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	$t \le 10 \text{ sec}$	R _{thJA}	20	25	°C/W
Maximum Junction-to-Ambient (MOSFET) ^a	Steady State		56	70	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.8	2.3	

Notes:

a. Surface Mounted on 1" x 1" FR4 Board.

b. See Solder Profile (*http://www.vishay.com/ppg?73257*). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

* Pb containing terminations are not RoHS compliant, exemptions may apply.



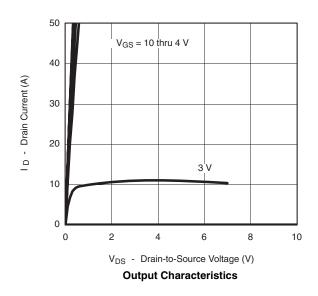
SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.0		3.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	1	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
	I _{DSS} -	V_{DS} = 30 V, V_{GS} = 0 V, T_{J} = 70 °C	c i i			μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	40			А	
		V _{GS} = 10 V, I _D = 18 A		0.0066	0.008	0	
Drain-Source On-State Resistance ^a	r _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 15 \text{ A}$		0.0090	0.011	Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 18 \text{ A}$		60		S	
Diode Forward Voltage ^a	V _{SD}	I _S = 3 A, V _{GS} = 0 V		0.70	1.1	V	
Dynamic ^b							
Total Gate Charge	Qg			13	18	nC	
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 18 A		5			
Gate-Drain Charge	Q _{gd}			4.0			
Gate Resistance	Rg		0.5	1.7	3.2	Ω	
Turn-On Delay Time	t _{d(on)}			18	27		
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		12	18	ns	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong\text{1}$ A, V_GEN = 10 V, R_G = 6 Ω		46	70		
Fall Time	t _f			19	30	115	
Source-Drain Reverse Recovery Time	t _{rr}	$I_F = 3 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		40	70	1	

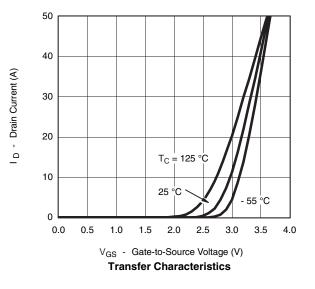
Notes:

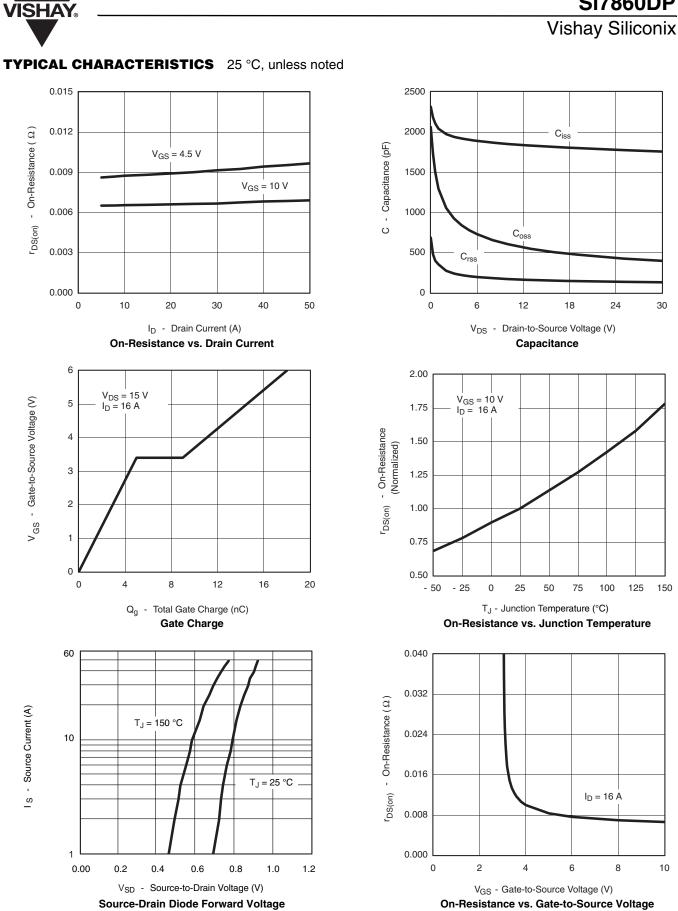
a. Pulse test; pulse width \leq 300 μs , duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless noted





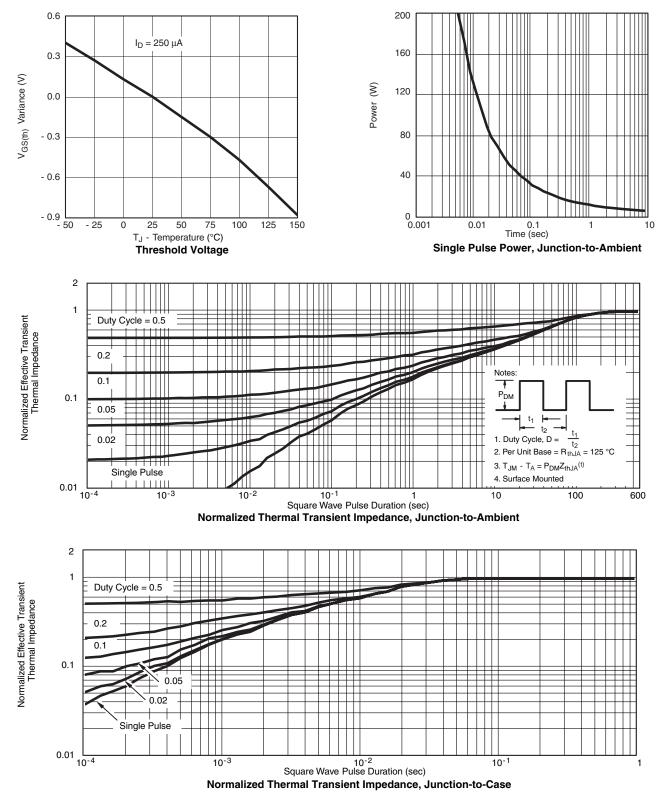


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Si7860DP

Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless noted



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?71854.



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